

C1812C222M2TACTU

Aliases (C1812C222M2TAC7800)

SMD Comm X8G HT150C, Ceramic, 2,200 pF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

Packaging

W	3.2mm +/-0.3mm	Toleran
T	1mm +/-0.10mm	Voltage
S	2.3mm MIN	Dielectr
В	0.6mm +/-0.35mm	Temper
		Temp. C
Packaging Specifications		Capacit

Specifications		
Capacitance	2,200 pF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	20%	
Voltage DC	200 VDC	
Dielectric Withstanding Voltage	500 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

Packaging Quantity	1000	Dissipation Factor	(
		Aging Rate	(

T&R, 180mm, Plastic Tape

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